

SAD
SA

83562

PATENT 1.22.02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re U.S. Patent Application)
Applicant: Peter LAHNOR and Stephan WEGE)
Serial No.: ~~Not Yet Assigned~~ 09/933304)
Filed: ~~Herewith~~ 8-20-01)
For: CMP PROCESS)

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

This is a Preliminary Amendment for entry in the above-identified application.

In the Claims:

Please amend the claims as follows:

- A
1. (amended) A CMP process for a contact hole or metal track etching, in which a liner deposited over the whole area on a dielectric after the patterning and a metalization layer deposited over the whole area on the liner, said metalization layer preferably being composed of tungsten or copper, are removed in regions by a chemical mechanical polishing process (CMP) which stops on the dielectric, wherein
B
at least in the regions surrounding the patterned portions on the dielectric, an auxiliary layer which can easily be removed by the CMP process is fashioned between dielectric and liner.